LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1764EQ-3.3#TRPBF **(Engineering Calculation)** DDPAK

TOTAL MASS (g): **1.401602**

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COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	**0.005437**	**1000000**	**3879.132**
Die Coat	Dow Corning	Silicone	67762-90-7	**0**	**0**	**0**
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.852419	998500	608174.8
		Iron (Fe)	7439-89-6	0	0	0
		Phosporus (P)	7723-14-0	0	0	0
		Zinc (Zn)	7440-66-6	0	0	0
		Nickel (Ni)	7440-02-0	0	0	0
		Silicon (Si)	7440-21-3	0	0	0
		Magnesium (Mg)	7439-95-4	0	0	0
		Tin (Sn)	7440-31-5	0.001281	1500	913.954
		Lead Frame Total:		**0.854981**	**1000000**	**610002.6**
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0
		Exter. Plating Sn	7440-31-5	0.009978218	1000000	7119.151
		External Plating Total:		**0.009978218**	**1000000**	**7119.151**
		Inter. Plating Ni	7440-02-0	0.004	740740.8	2853.877
		Inter. Plating Ag	7440-22-4	0.0014	259259.3	998.8569
		Internal Plating Total:		**0.0054**	**1000000**	**3852.734**
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0	0	0
		Tin (Sn)	7440-31-5	0.000121	50000	86.32977
		Lead (Pb)	7439-92-1	0.002297	950000	1638.839
		Silica (SiO2)	60676-86-0	0	0	0
		Metal Oxide		0	0	0
		Resin (EP)		0	0	0
		Die Attach Total:		**0.002418**	**1000000**	**1725.169**
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.053704	103000	38316.15
		Bromine (Br)	40039-93-8	0	0	0
		Silica (SiO2)	60676-86-0	0.466653	895000	332942.5
		Antimony Trioxide (Sb2O3)	1309-64-4	0	0	0
		Metal Hydroxid		0	0	0
		Carbon Black (C)	1333-86-4	0.001043	2000	744.1484
		Encapsulation Total:		**0.5214**	**1000000**	**372002.8**
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	**0.001988**	**1000000**	**1418.377**